

# Chinmay Rozekar

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## PROFESSIONAL SUMMARY

- Versatile engineer with 4+ years in Silicon Validation, adept in both Pre-Silicon and Post-Silicon environments, specializing in system-level testing and product quality enhancement.
- Committed to leveraging technical expertise for reducing operational costs and enhancing product specifications.
- Excels in cross-functional team collaboration, test automation with Python, C/C++, and Java, and innovative problem-solving.

## EXPERIENCE

<b>Product Development Engineer</b> <i>Advanced Micro Devices (AMD)</i> <i>System Level Testing (SLT)</i>	July 2020 – Present <i>Austin, TX</i>
<ul style="list-style-type: none"><li>• Led system-level testing for AMD's Ryzen 8040 'Hawkpoint' series, Accelerated Processing Units (APUs), ensuring adherence to customer environment standards.</li><li>• Spearheaded Test Time Reduction (TTR), eliminated redundant tests, for reducing operational costs through DPPM Yield Analysis in Production.</li><li>• Experienced in monitoring production yield and debugging/root cause analysis of high-Pareto items in production fallout.</li><li>• Experienced in performing SoC Characterization for Product Definition by setting Test-Program flows on volume testing.</li><li>• Maintained the test program codebase repository using Atlassian BitBucket, overseeing the development and release of test content throughout the product roadmap.</li><li>• Collaborated with Diagnostic, BIOS, and Design teams to enhance CPU performance features, contributing to product specification improvements.</li><li>• Experienced in Customer RMA Debug issues through secure fuse unlocking during Field Return Analysis (FRA).</li><li>• Established and managed an in-house server farm and APU client board setup, ensuring robust testing environments and streamlining development.</li></ul>	

<b>Product Engineering Co-Op</b> <i>Advanced Micro Devices (AMD)</i>	Jan. 2019 – Dec.2019 <i>Austin, TX</i>
<ul style="list-style-type: none"><li>• Designed and automated test programs for Human Body Model Testing, reducing Engineering time by 90%.</li><li>• Reverse-engineered and redesigned a 20-year-old robotic graphical user interface in Python, reducing engineering time by 95%.</li><li>• Conducted stress tests on AMD products according to industry standards, qualifying products for production.</li><li>• Performed scheduled calibration and waveform verification for preventive maintenance as per ISO 9000 standards</li><li>• Conducted Design of Experiments on AMD products for Capacitive Modeling to optimize protection circuitry</li></ul>	

<b>Graduate Research Assistant</b> <i>Rochester Institute of technology</i>	Jan 2020 – May 2020 <i>Rochester, NY</i>
<ul style="list-style-type: none"><li>• Developed a process flow for thin film IC development, covering various fabrication steps</li><li>• Designed and simulated NMOS devices to determine sub-threshold voltages and model leakage current</li><li>• Conducted electrical device characterization to optimize gate oxide thickness on NMOS devices.</li></ul>	

## TECHNICAL SKILLS

<b>Process Engineering:</b> Thin Films, PVD, CVD, Sputtering, Dry Etch, Metrology, Characterization
<b>Languages:</b> Java, Python, BASH, C/C++, SQL, HTML/CSS, XML, Markdown, MATLAB, Perl
<b>Libraries:</b> Matplotlib, Pandas, Numpy, Scikit-learn, Selenium
<b>Developer Tools:</b> Git, Jira, Confluence, Linux, CI/CD, IntelliJ Idea, VS Code, PyCharm, Eclipse, Jupyter, Anaconda, JSON, Notepad++, LaTeX
<b>Protocols:</b> JTAG, PCIE, DFT, Boundary SCAN, ATPG
<b>Simulation:</b> KiCAD, SolidWorks, COMSOL Multiphysics, Silvaco-Athena, Pyxis(Mentor Graphics)
<b>Data Analysis:</b> Excel, Power-BI, JMP, Python

## PROJECTS

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<b>Review of Thin Film Technologies for Flexible Electronics</b>	Jan 2020 – May. 2020
• Designed a simulation model for growing a 1 $\mu\text{m}$ layer of flexible crystalline Si substrate on top of Tungsten metal layer using SOI method in Silvaco Athena.	
<b>A Thermally actuated four-legged MEMS based Silicon Micro-robot</b>	May 2018 – Dec. 2018
• Designed and fabricated a thermally actuated MEMS based Silicon micro-robot. Modeled design in CAD / Solidworks and Heat Transfer using COMSOL multi-physics FEA.	

## EDUCATION

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<b>Rochester Institute of Technology</b>	Rochester, NY
<i>Master of Science, Electrical Engineering</i>	<i>Aug. 2017 – May 2020</i>
<b>Bharati Vidyapeeth University</b>	Pune, India
<i>Bachelor of Technology, Electrical Engineering</i>	<i>Aug. 2012 – June 2016</i>